Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.009”**

**.009”**

**Top Material: Al**

 **Backside Material: Au**

**Bond Pad Size: .0048” X .0048”**

**Backside Potential: CATHODE**

**Mask Ref: CPD102X**

**APPROVED BY: DK DIE SIZE .009” X .009” DATE: 11/4/16**

**MFG: CENTRAL SEMI THICKNESS .006” P/N: CMPD6263**

**DG 10.1.2**

#### Rev B, 7/1